

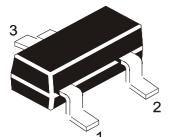
Continental Device India Limited

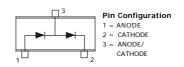
An ISO/TS 16949, ISO 9001 and ISO 14001 Certified Company





SILICON PLANAR HIGH SPEED SWITCHING DIODES





BAV99

SOT-23 Formed SMD Package

This product is available in AEC-Q101 Compliant also Marking

BAV99 = A7

NOTE: For AEC-Q101 compliant products, please use suffix -AQ in the part number while ordering High-Speed Switching Series Diode Pair

ABSOLUTE MAXIMUM RATINGS (Rating Per Diode)

DESCRIPTION	SYMBOL	VALUE	UNIT	
Repetitive Peak Reverse Voltage	V_{RRM}	100	V	
Reverse Voltage	V_R	100	V	
Forward Current (DC)	I _F	215	mA	
Repetitive Peak Forward Current	I _{FRM}	500	mA	
Non Repetitive Peak Forward Current				
(per crystal)				
t=1 ms	I _{FSM}	4.0	Α	
t=1 ms	I _{FSM}	1.0	А	
t=1 s	I _{FSM}	0.5	А	
Power Dissipation up to T _a =25°C	P _D	250	mW	
Junction Temperature	T _j	150	°C	
Ambient Temperature	T _{amb}	- 65 to +150	°C	
Storage Temperature Range	T _{stg}	- 65 to +150	°C	

THERMAL RESISTANCE

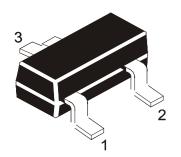
Junction to Ambient in free air	R _{th (j-a)}	500	K/W
Junction to Solder Point	R _{th (j-sp)}	360	K/W

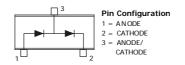
ELECTRICAL CHARACTERISTICS (T_a=25° C unless specified otherwise) per diode

DESCRIPTION	SYMBOL	TEST CONDITION	MIN	MAX	UNIT
Forward Voltage	V_{F}	$I_F = 1mA$		0.715	V
		$I_F = 10mA$		0.855	V
		$I_F = 50mA$		1.0	V
		$I_F = 150 \text{mA}$		1.25	V
Reverse Current	I _R	V _R =25V		30	nA
		$V_R = 25V, T_J = 150^{\circ}C$		30	μΑ
		$V_R=80V$		0.5	μΑ
		$V_R = 80V, T_J = 150^{\circ}C$		50	μΑ

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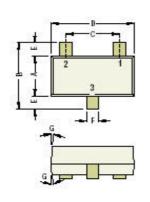
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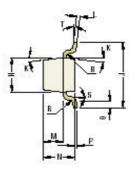
ELECTRICAL CHARACTERISTICS (T_a=25° C unless specified otherwise) per diode

DESCRIPTION	SYMBOL	TEST CONDITION	MIN	MAX	UNIT
Diode Capacitance	C _d	V _R =0V, f=1MHz		1.5	pF
Forward Recovery Voltage	V_{FR}	I _F =10mA, t _r =20ns		1.75	V
Reverse Recovery Time	t _{rr}	I_F =10mA, to I_R =10mA, measured at I_R =1.0mA, R_L =100 Ω		4.0	ns
Reverse Charge When Switched Time	Qs	I_F =10mA to V_R =5 V , R_L =100 Ω		45	рС

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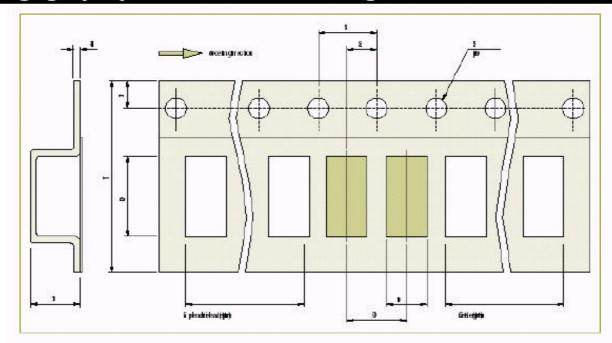




DIM	Min	Max
Α	1.20	1.40
В	2.10	2.64
C	1.85	1.95
D	2.80	3.04
E	0.54	0.67
F	0.30	0.50
G	3	3º
Н	()	1.30
J	2.10	2.64

DIM	Min	Max	
К	7	ra .	
L	0.08	0.20	
M	0.58	0.62	
N	0.70 0.21	1.02	
0		_	
Р	0.02	0.15	
R	-	0.08	
S	2°	8"	
T	2°	10°	

Packaging Tape Specifications for SMD Packages

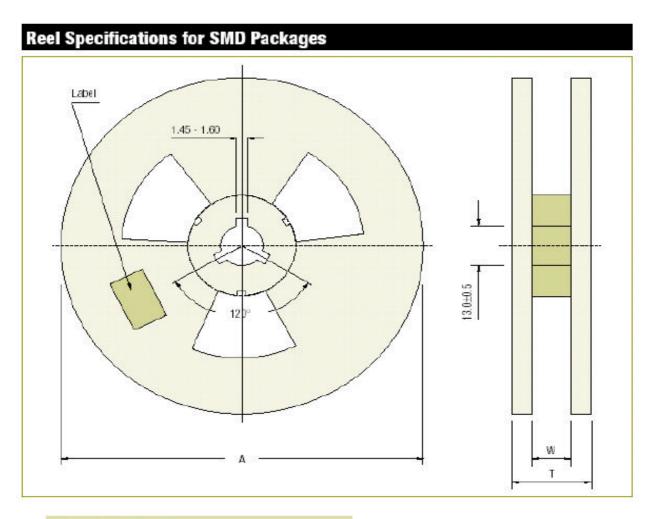


SMD Tape Specifications (8-12 mm)

Device D1 D2	D2	D3	Tí	12	13	T4	SI	S2	S3	
				V.	Nax	Nax			Dia	
	m	m	mn	mm	nm	nn	nn	m	nyn	mm
SOT-23	3.2±0.1	2.8±0.1	4.0±0.1	1.0±0.2	1.75±0.1	1.90	0.35	4.0±0.1	2.0±0.1	1.5±0.1

Packaging				M . 1999				
Package / Case Type	T & R: Tape and feet Bulk: I Packaging Type	Std. Packing	Tune and Lam	InnerCarton	. 5		Outer Carton	
		Oty	Qty	Size L x W x f	Gross Weight	Qty	Size Lx W x H	Gross Weight
			877	(cm)	(Kg)	- 10	(cm)	(Kg)
SOT-23	T&R	3,000	15K	19x19x8	0.6	51K	23 x 13 x 23	2.2
	T&R	3,000	15K	19x19x8	0.6	408K	48 x 48 x 51	20.2
	T&R	10,000	50K	35.5 x 35.5 x 8.9	2.4	350K	48 x 48 x 51	19.2

SOT-23 Formed SMD Package



Reel Specifications

Package	Tape	Red Dia.	Devices	Imide	Reel
	Width		per Reel	Thickness	Thickness
		A - Max	and M00	W	T - Max
S0T-23	1	180	3,000	8.4±2	14.4
	1	330	10,000	8.4±2	14.4

Customer Notes BAV99

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Component Disposal Instructions

- CDIL Semiconductor Devices are RoHS compliant, customers are requested to please dispose as per prevailing Environmental Legislation of their Country.
- 2. In Europe, please dispose as per EU Directive 2002/96/EC on Waste Electrical and Electronic Equipment (WEEE).

Disclaimer

The product information and the selection guides facilitate selection of the CDIL's Semiconductor Device(s) best suited for application in your product(s) as per your requirement. It is recommended that you completely review our Data Sheet(s) so as to confirm that the Device(s) meet functionality parameters for your application. The information furnished on the CDIL Web Site/CD are believed to be accurate and reliable. CDIL however, does not assume responsibility for inaccuracies or incomplete information. Furthermore, CDIL does not assume liability whatsoever, arising out of the application or use of any CDIL product; neither does it convey any license under its patent rights nor rights of others. These products are not designed for use in life saving/support appliances or systems. CDIL customers selling these products (either as individual Semiconductor Devices or incorporated in their end products), in any life saving/support appliances or systems or applications do so at their own risk and CDIL will not be responsible for any damages resulting from such sale(s).

CDIL strives for continuous improvement and reserves the right to change the specifications of its products without prior notice.



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